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Chen et al.

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(54) **LIGHT EMITTING DIODE PACKAGE**

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(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/180**

(58) **Field of Classification Search**
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H01L 27/156; H01L 31/02; H01L 33/00;
H01L 33/04; H01L 33/08; H01L 33/10;
H01L 33/20; H01L 33/38; H01L 33/42;
H01L 33/4862; H01L 33/483; H01L 33/486
USPC D13/180; D26/1; 257/79, 80, 81, 88,
257/89, 95, 98, 99, 100, E33.058; 313/483,
313/498, 500; 362/555, 800

See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

D505,397	S	*	5/2005	Asakawa	D13/180
D517,025	S	*	3/2006	Asakawa	D13/180
D568,261	S	*	5/2008	Lee et al.	D13/180
D576,573	S	*	9/2008	Kobayakawa	D13/180
D592,617	S	*	5/2009	Bando	D13/180
D593,967	S	*	6/2009	Fushimi	D13/180
D619,110	S	*	7/2010	Lin et al.	D13/180
D624,885	S	*	10/2010	Lin et al.	D13/180
D662,902	S	*	7/2012	Shieh et al.	D13/180
D674,361	S	*	1/2013	Lin et al.	D13/180
D693,780	S	*	11/2013	Chen et al.	D13/180
D695,239	S	*	12/2013	Ko et al.	D13/180
D698,047	S	*	1/2014	Sasaoka et al.	D26/1
D698,742	S	*	2/2014	Niikura et al.	D13/180
2012/0104426	A1	*	5/2012	Chan et al.	257/89

* cited by examiner

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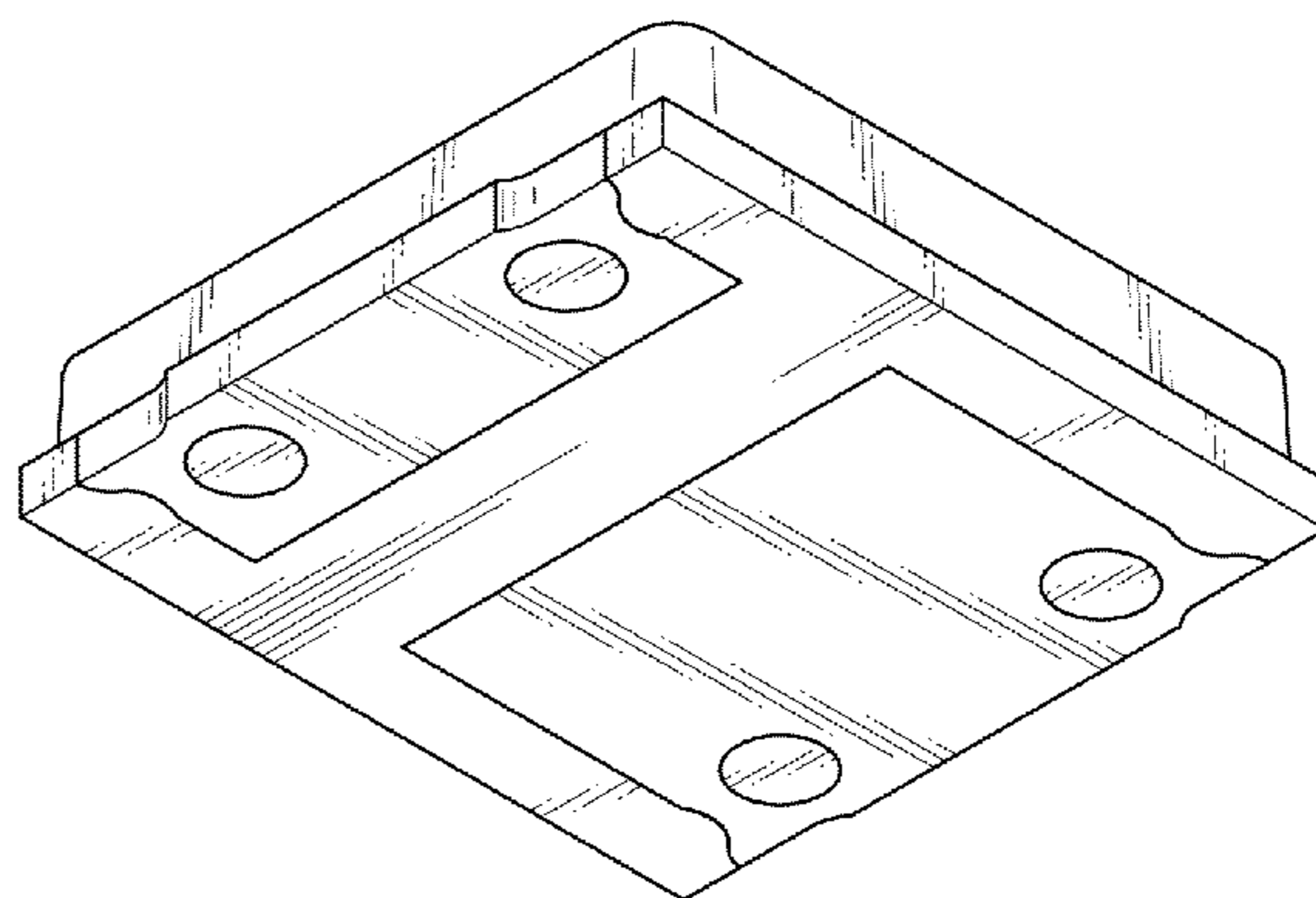
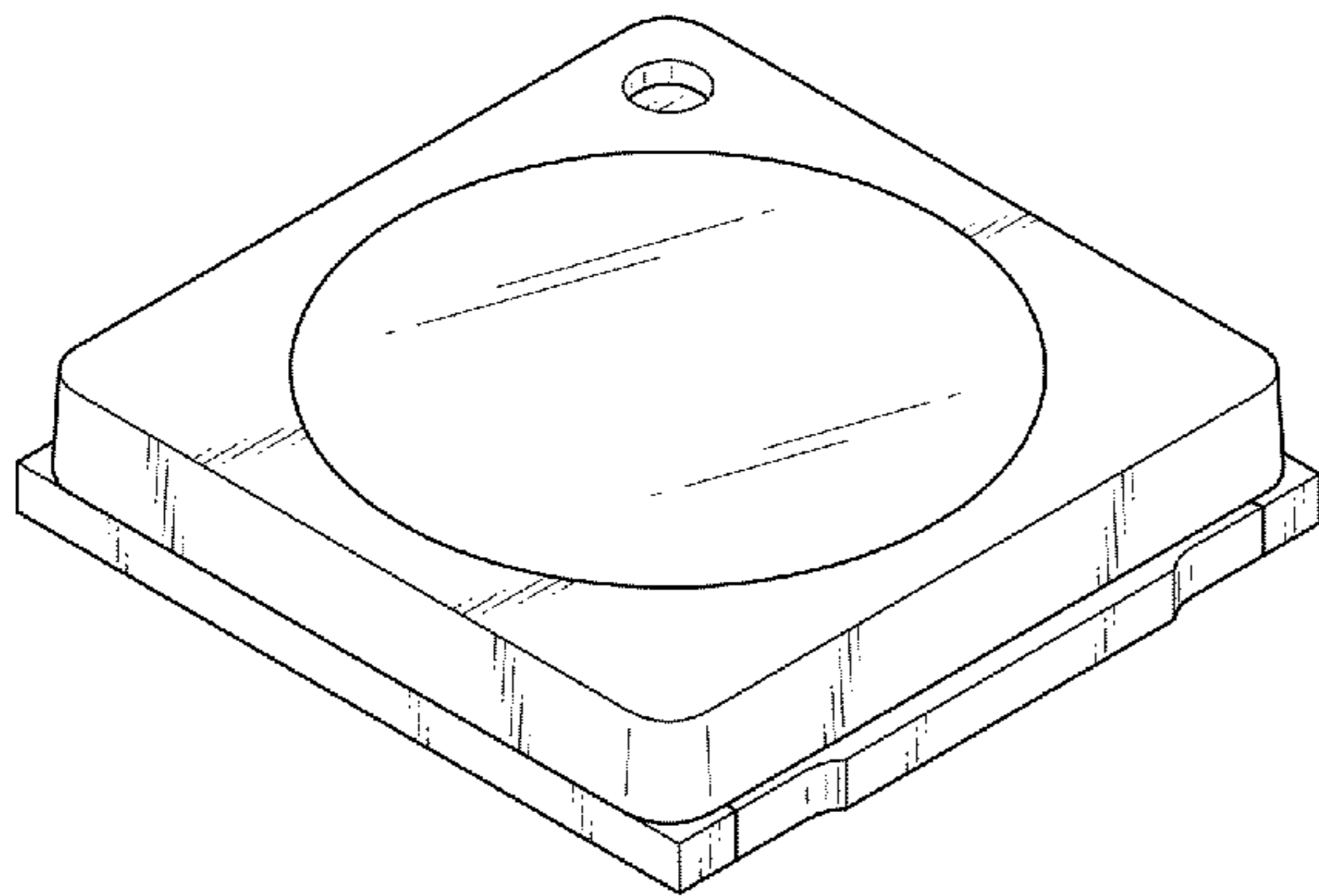
(57) **CLAIM**

The ornamental design for a light emitting diode package, as shown and described.

DESCRIPTION

FIG. 1 is a front perspective view of a light emitting diode package showing the new design;
FIG. 2 is another perspective view thereof;
FIG. 3 is a front elevational view thereof;
FIG. 4 is a rear elevational view thereof;
FIG. 5 is a left side elevational view thereof;
FIG. 6 is a right side elevational view thereof;
FIG. 7 is a top plan view thereof; and,
FIG. 8 is a bottom plan view thereof.

1 Claim, 8 Drawing Sheets



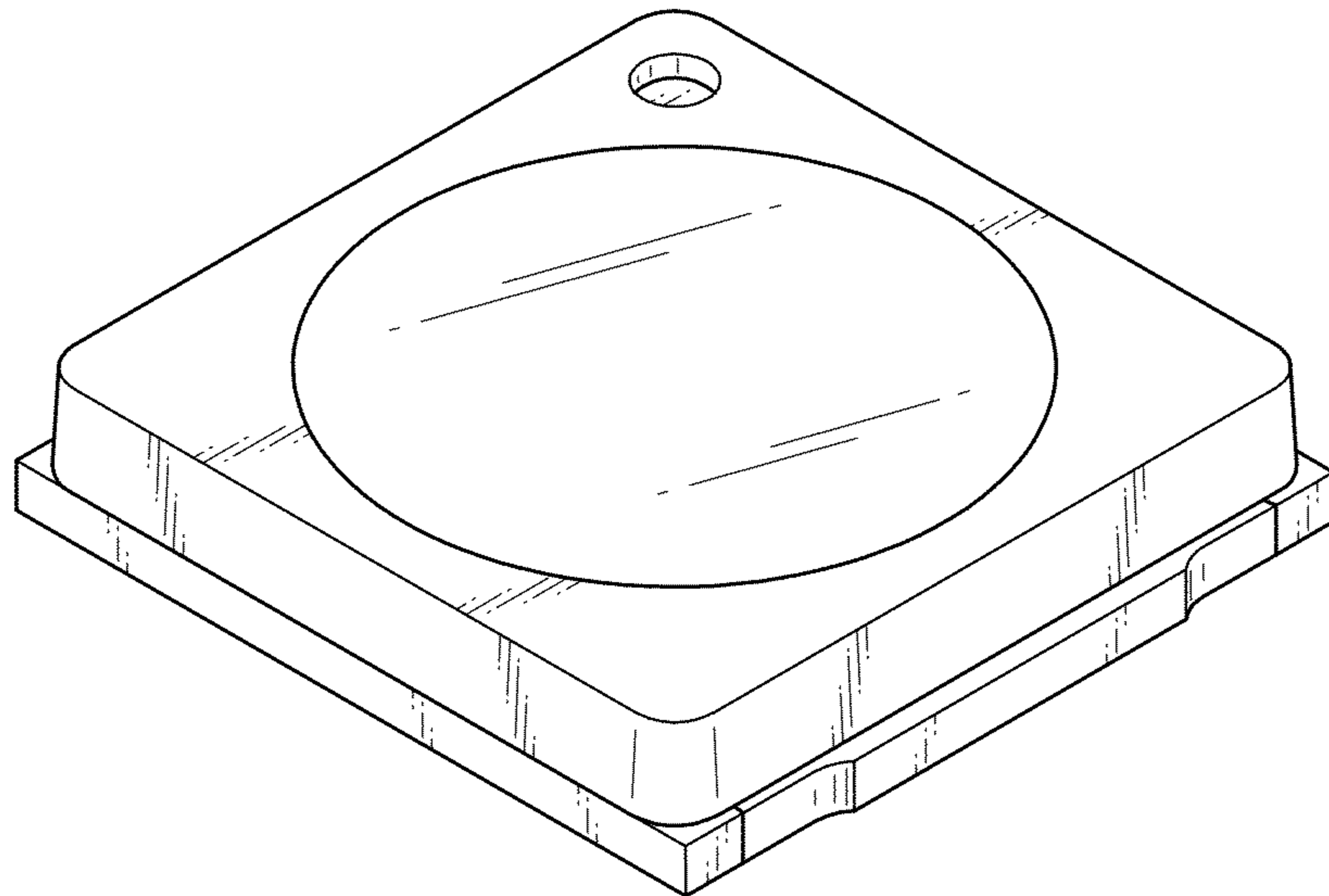


FIG. 1

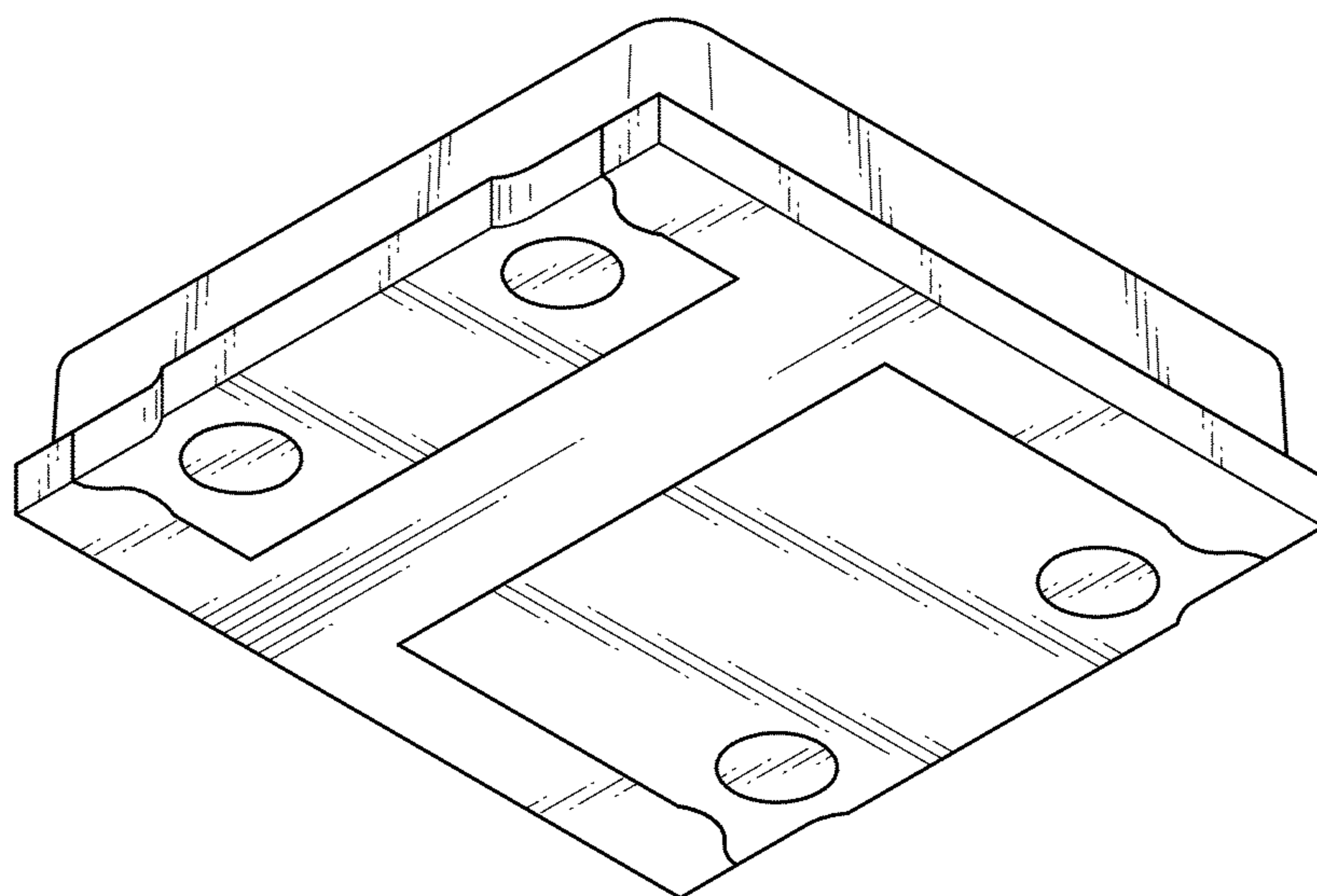


FIG.2

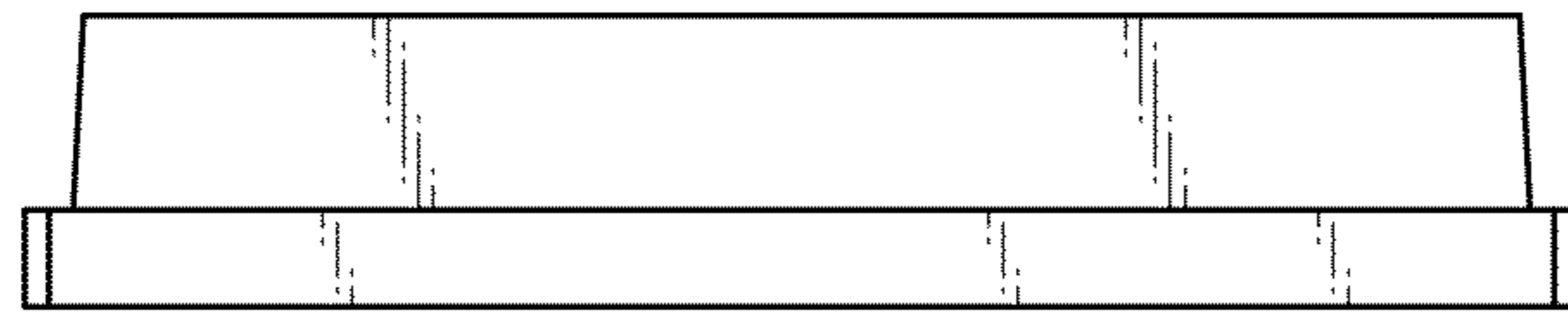


FIG.3

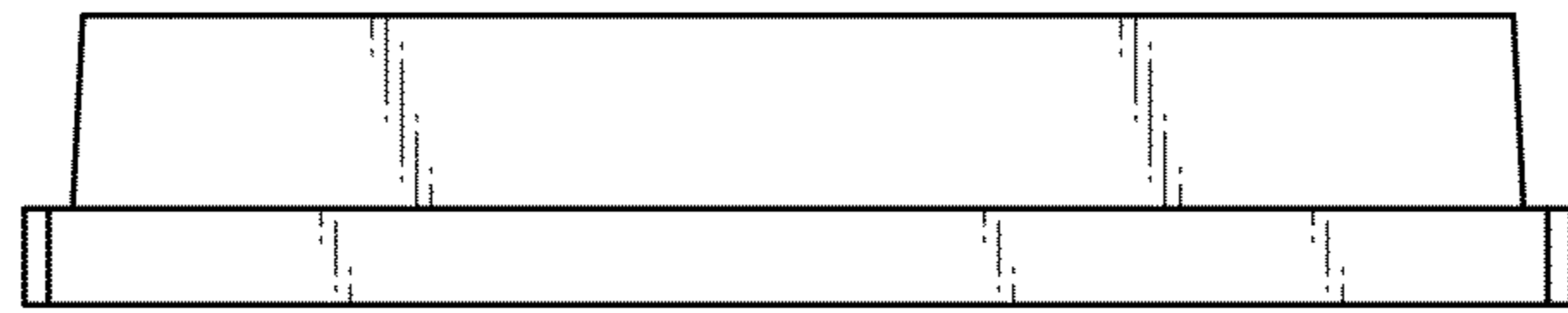


FIG.4

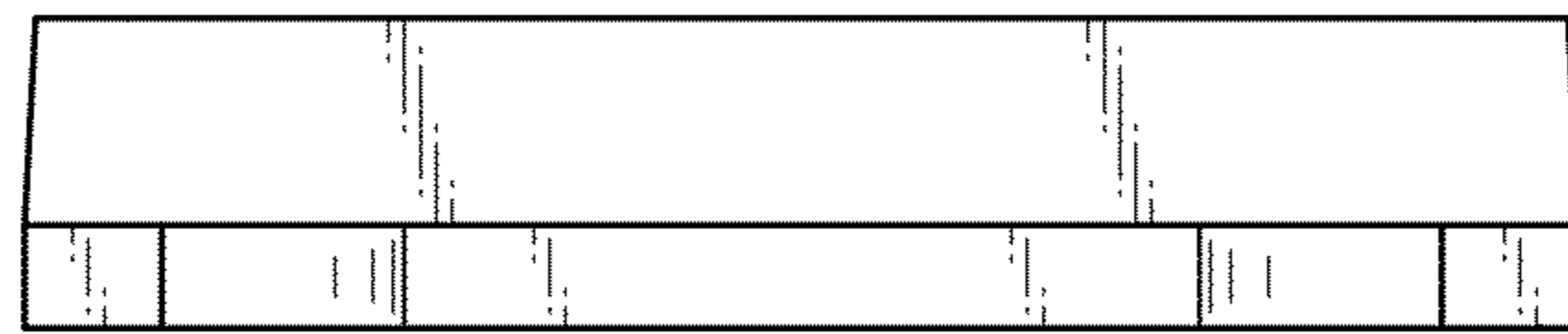


FIG.5

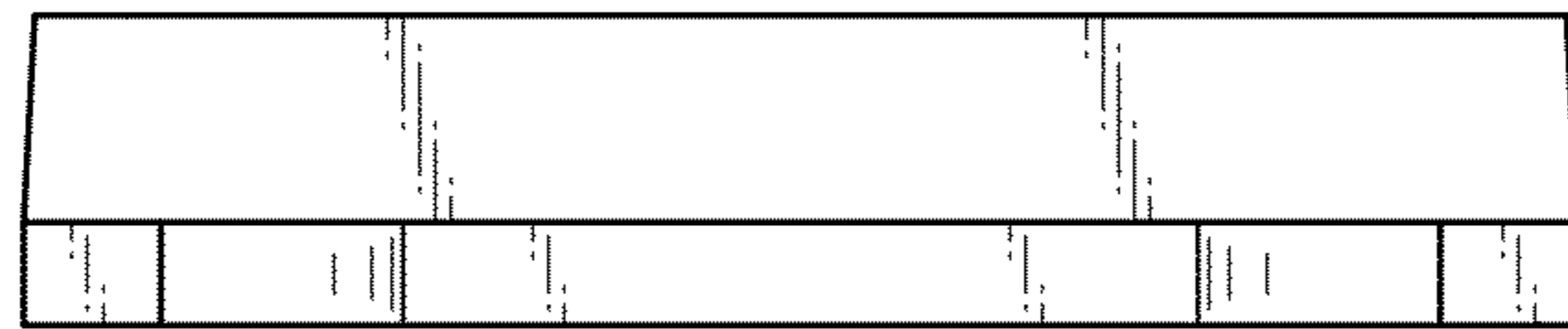


FIG.6

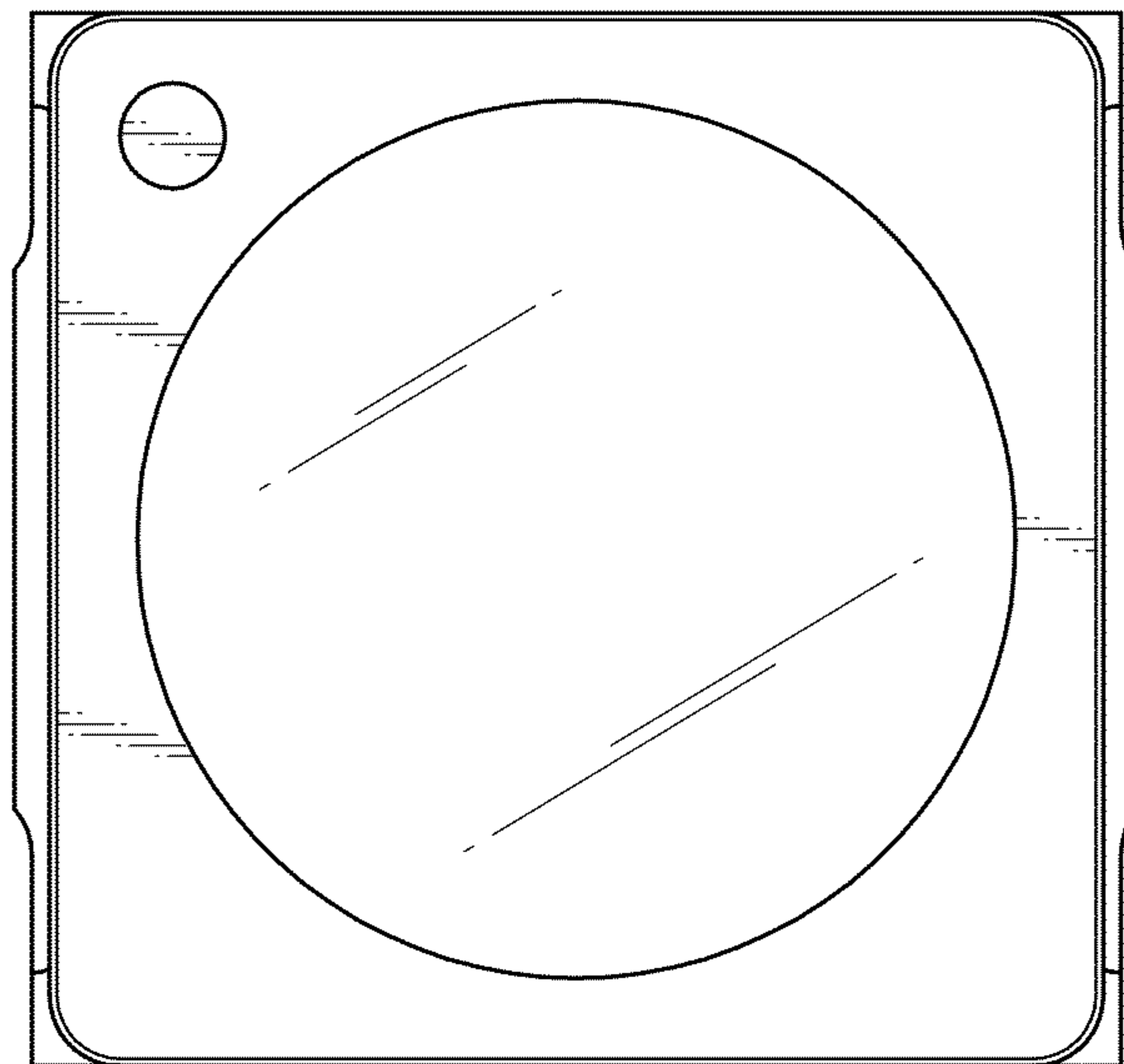


FIG. 7

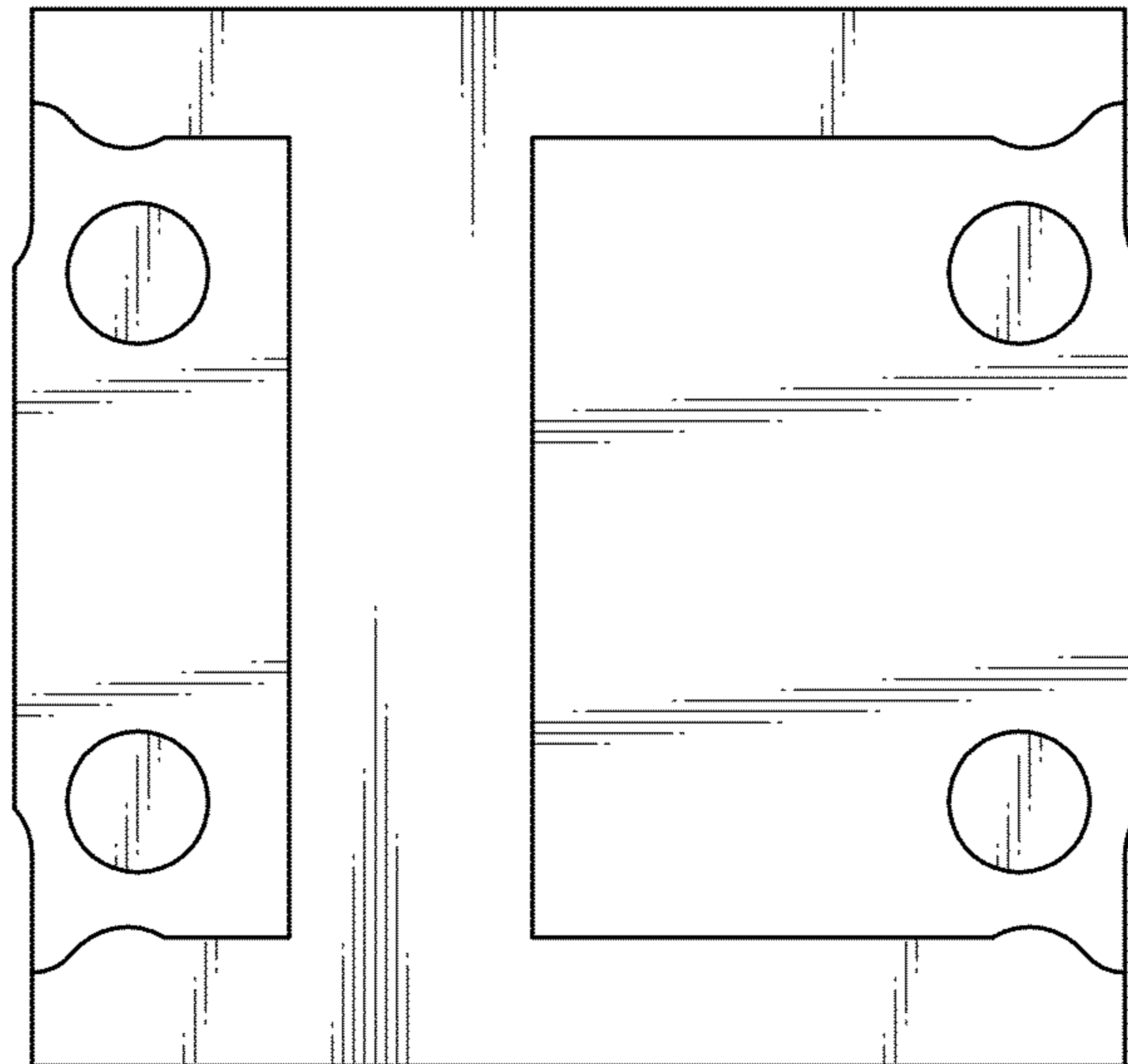


FIG.8